

## 40A 1200V N-channel SiC Power MOSFET

### 1 Description

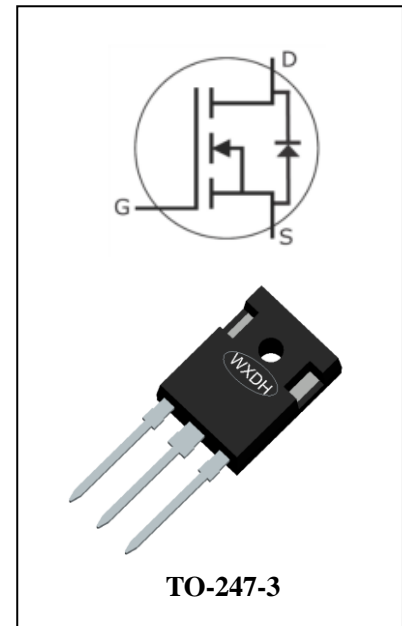
This product family offers state of the art performance. It is designed for high frequency applications where high efficiency and high reliability are required.

### 2 Features

- Higher System Efficiency
- Reduced Cooling Requirements
- Increased Power Density
- Increased System Switching Frequency

### 3 Applications

- Power Supplies.
- High Voltage DC/DC Converters.
- Motor Drives.
- Switch Mode Power Supplies
- Pulsed Power applications



TO-247-3

$$V_{DSS} = 1200V$$

$$R_{DS(on)} (TYP) = 75m\Omega$$

$$I_D = 41A$$

### 4 Electrical Characteristics

#### 4.1 Absolute Maximum Rating ( $T_c=25^\circ C$ , unless otherwise noted)

Parameter	Symbol	Test Conditions	Value	Units
Drain-to-Source Voltage	$V_{DSmax}$	$V_{GS}=0V, I_D=100\mu A$	1200	V
Gate-Source Voltage	$V_{GSmax}$	Absolute maximum values	-10/+25	V
Gate-Source Voltage	$V_{GSop}$	Recommended operational values	-5/+20	V
Continuous Drain Current	$I_D$	$V_{GS}=20V, T_C=25^\circ C$	41	A
		$V_{GS}=20V, T_C=100^\circ C$	28	A
Pulsed Drain Current <sup>(1)</sup>	$I_{D(PULSE)}$	Pulse width $t_p$ limited by $T_{Jmax}$	80	A
Power Dissipation	$P_D$	$T_c=25^\circ C, T_J=175^\circ C$	208	W
Junction Temperature Range	$T_j$		-55~175	$^\circ C$
Storage Temperature Range	$T_{stg}$		-55~175	$^\circ C$

#### 4.2 Thermal Characteristics

Parameter	Symbol	Rating	Unit
Thermal Resistance, Junction to Case-sink	$R_{thJC}$	0.72	$^\circ C/W$
Thermal Resistance, Junction to Ambient	$R_{thJA}$	40	$^\circ C/W$

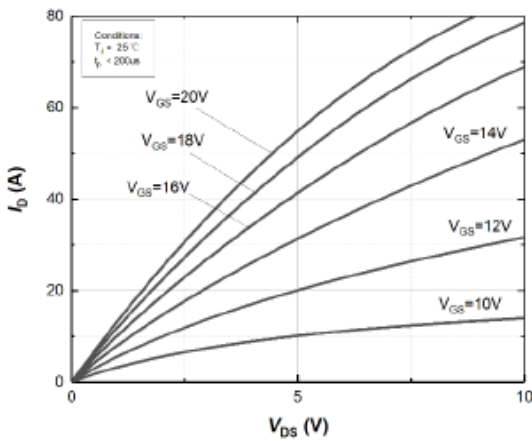
**4.3 Electrical Characteristics** (Tc=25°C, unless otherwise noted)

Parameter	Symbol	Test Condition	Value			Units
			Min	Typ	Max	
Drain-to-Source Breakdown Voltage	BV <sub>DSS</sub>	I <sub>D</sub> =100uA, V <sub>GS</sub> =0V	1200	---	---	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =1200V, V <sub>GS</sub> =0V	---	1	50	μA
Gate-to-Source Leakage	I <sub>GSS+</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =20V	---	5	250	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =5mA	---	3	---	V
		V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =5mA, T <sub>J</sub> =175°C	---	2.3	---	V
Drain-to-Source on-state Resistance	R <sub>Ds(on)</sub>	V <sub>GS</sub> =18V, I <sub>D</sub> =20A	---	75	---	mΩ
		V <sub>GS</sub> =18V, I <sub>D</sub> =20A, T <sub>J</sub> =175°C	---	125	---	
Transconductance	g <sub>fs</sub>	V <sub>GS</sub> =20V, I <sub>D</sub> =20A	---	9	---	S
		V <sub>GS</sub> =20V, I <sub>D</sub> =20A, T <sub>J</sub> =175°C	---	7	---	
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =1000V, f=1.0MHz, V <sub>AC</sub> =25mV	---	1374	---	pF
Output Capacitance	C <sub>oss</sub>		---	63	---	
Reverse Transfer Capacitance	C <sub>rss</sub>		---	3.5	---	
Turn-On Switching Energy	E <sub>ON</sub>	V <sub>DS</sub> =800V, V <sub>GS</sub> =-4V/20V I <sub>D</sub> =20A, R <sub>G(ext)</sub> = 5Ω, L=276μH	---	73	---	μJ
Turn-Off Switching Energy	E <sub>OFF</sub>		---	145	---	
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DS</sub> =800V, V <sub>GS</sub> =-4V/20V, I <sub>D</sub> =20A, R <sub>G(ext)</sub> = 5Ω, R <sub>L</sub> =30Ω	---	8.7	---	nS
Turn-on Rise Time	t <sub>r</sub>		---	18.3	---	
Turn-off Delay Time	t <sub>d(off)</sub>		---	17.2	---	
Turn-off Fall Time	t <sub>f</sub>		---	9.8	---	
Internal Gate Resistance	R <sub>G(int)</sub>	f=1MHz, V <sub>AC</sub> =25mV	---	2	---	Ω
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =800V, V <sub>GS</sub> =-5V/20V, I <sub>D</sub> =20A	---	66	---	nC
Gate-to-Source Charge	Q <sub>gs</sub>		---	15	---	
Gate-to-Drain("Miller") Charge	Q <sub>gd</sub>		---	30	---	
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage <sup>(3)</sup>	V <sub>SD</sub>	V <sub>GS</sub> =-4V, I <sub>SD</sub> =10A	---	3.7	---	V
		V <sub>GS</sub> =-4V, I <sub>SD</sub> =10A, T <sub>J</sub> =175°C	---	3.1	---	V
Diode Forward Current	I <sub>S</sub>	V <sub>GS</sub> =-4V, T <sub>C</sub> =25°C	---	35	---	A
Reverse Recovery Time <sup>(3)</sup>	t <sub>rr</sub>	V <sub>R</sub> =800V, I <sub>SD</sub> =20A	---	36	---	nS
Reverse Recovery Charge <sup>(3)</sup>	Q <sub>rr</sub>		---	145	---	nC
Peak Reverse Recovery Current	I <sub>rrm</sub>		---	7.1	---	A

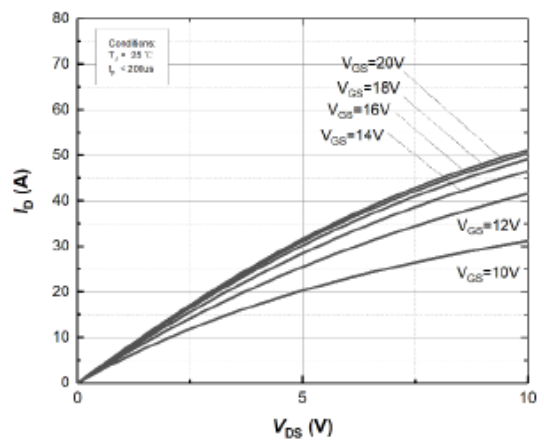
**Notes:**

- 1: Repetitive rating, pulse width limited by maximum junction temperature.
- 2: Surface mounted on FR4 Board, t<sub>s</sub>≤10sec.
- 3: Pulse width ≤ 300μs, duty cycle ≤ 2%.

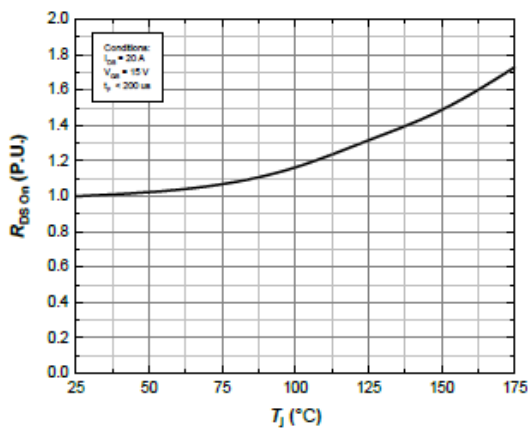
**5 Typical characteristics diagrams**



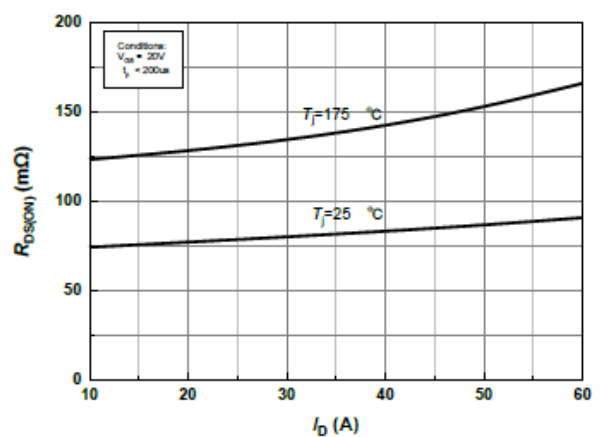
**Figure 1. Output characteristics at  $T_j=25^\circ\text{C}$**



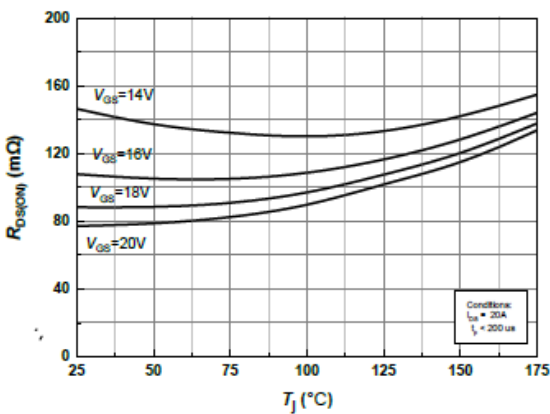
**Figure 2. Output characteristics at  $T_j=175^\circ\text{C}$**



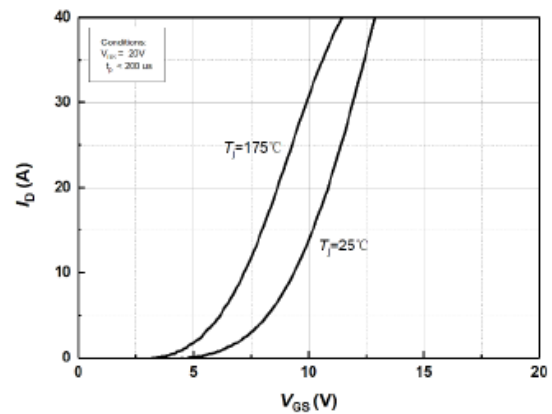
**Figure 3. Normalized On-Resistance vs. Temperature**



**Figure 4. On-Resistance vs. Drain current for Various Temperature**

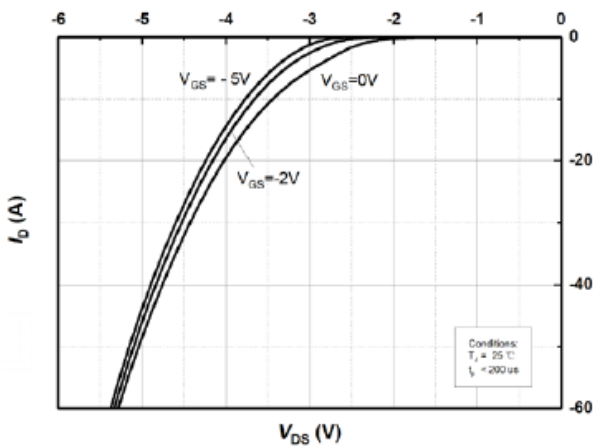


**Figure 5. On-Resistance vs. Temperature for Various Gate Voltage**

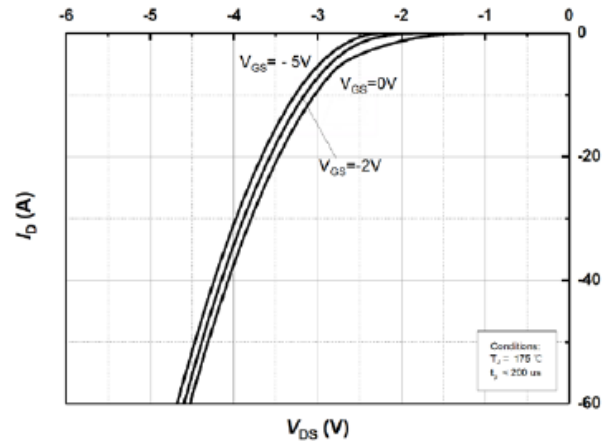


**Figure 6. Transfer Characteristics for Various Junction Temperatures**

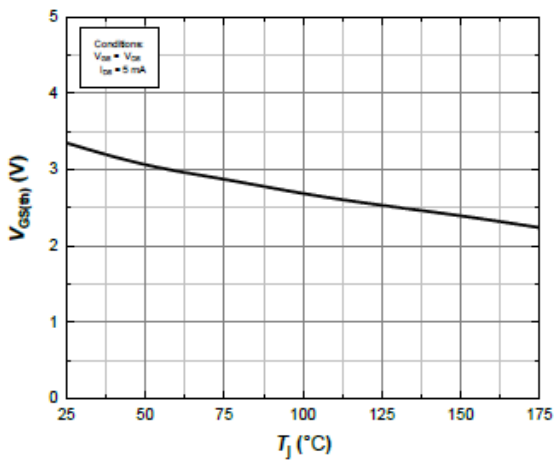
**5 Typical characteristics diagrams(continues)**



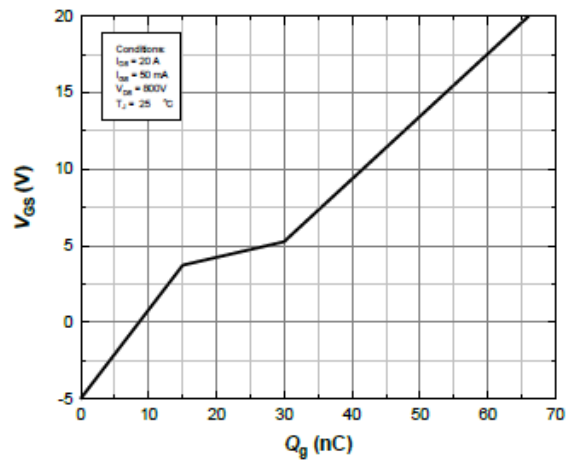
**Figure 7. Body Diode Characteristics at Tj=25°C**



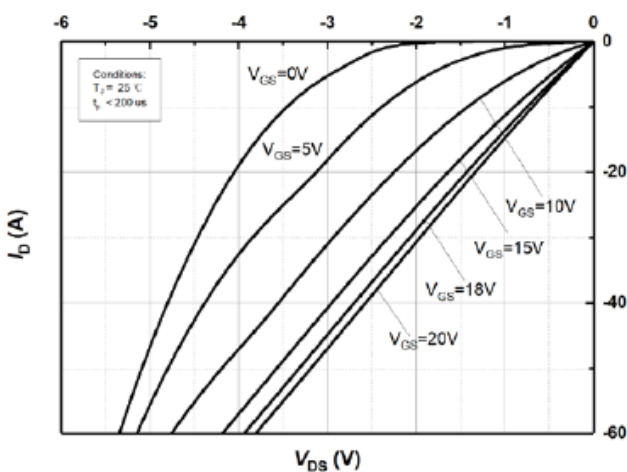
**Figure 8. Body Diode Characteristics at Tj=175°C**



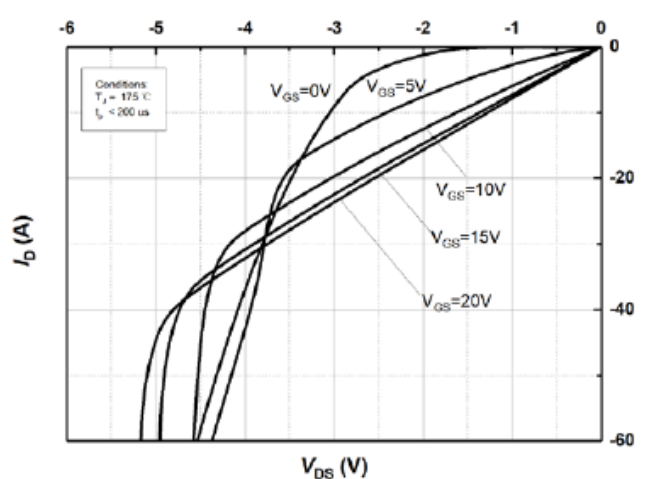
**Figure 9. Threshold Voltage vs. Temperature**



**Figure 10 Gate Charge Characteristics**

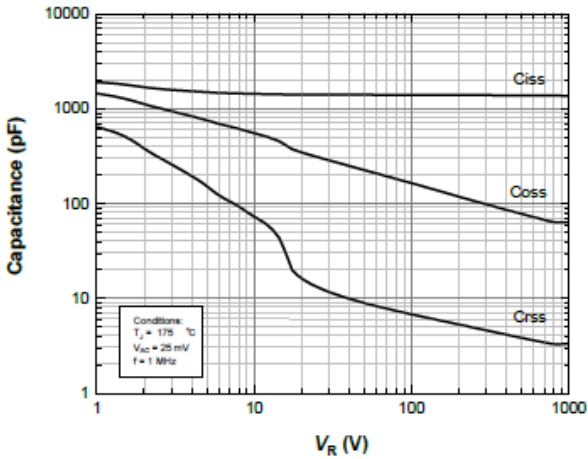


**Figure 11. 3rd Quadrant Characteristic at Tj=25°C**

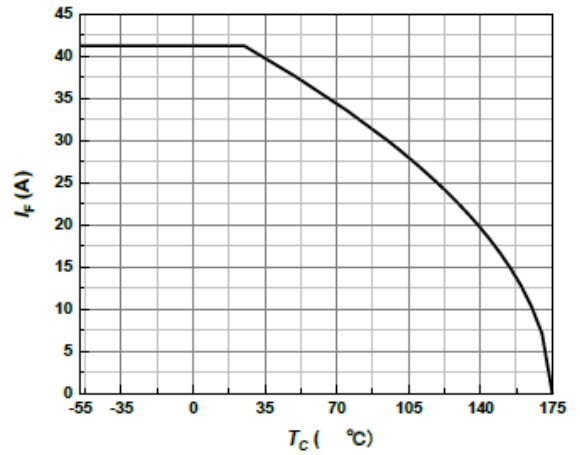


**Figure 12. 3rd Quadrant Characteristic at Tj=175°C**

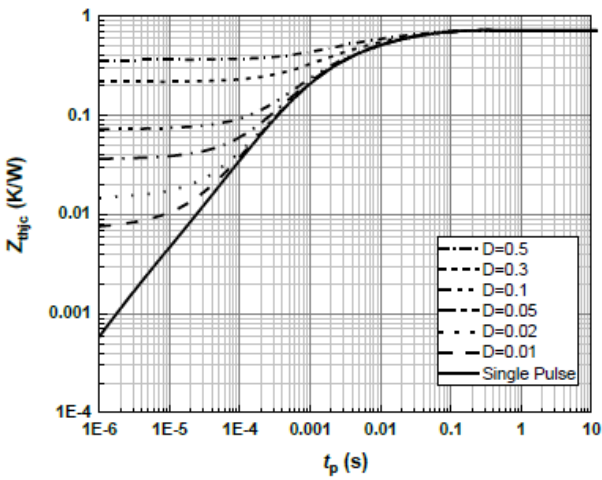
**5 Typical characteristics diagrams(continues)**



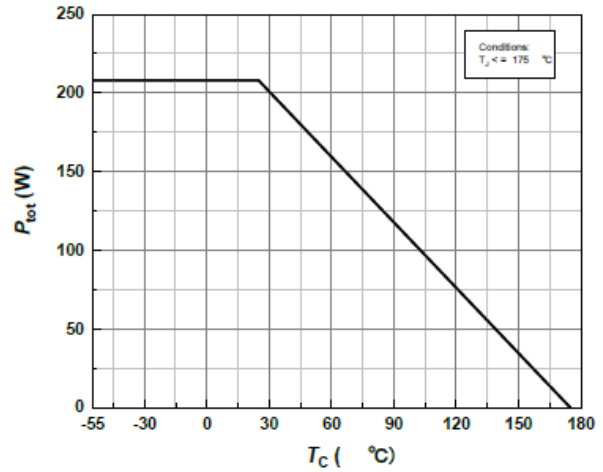
**Figure 13. Capacitances vs. Drain-Source Voltage (0 – 1000V)**



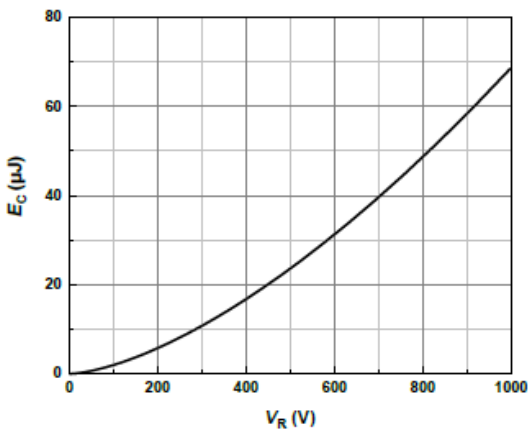
**Figure 14. Continuous Drain Current Derating vs Case Temperature**



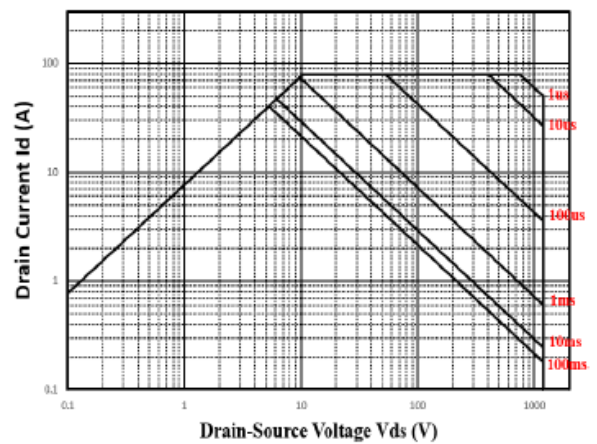
**Figure 15. Transient Thermal Impedance (Junction – Case)**



**Figure 16. Maximum Power Dissipation Derating vs. Case Temperature**



**Figure 17. Output Capacitor Stored Energy**



**Figure 18. Safe Operating Area**

5 Typical characteristics diagrams(continues)

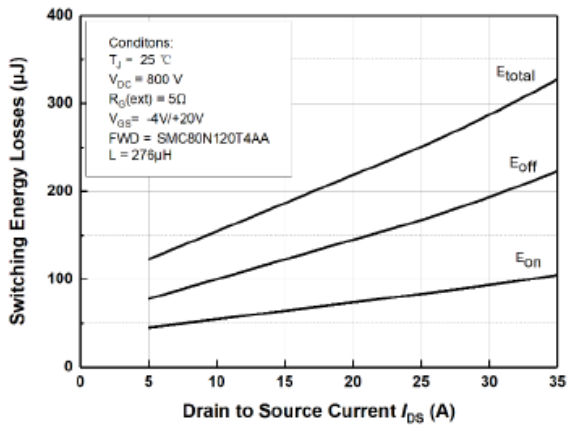


Figure 19. Clamped Inductive Switching Energy vs. Drain Current( $V_{DD} = 800V$ )

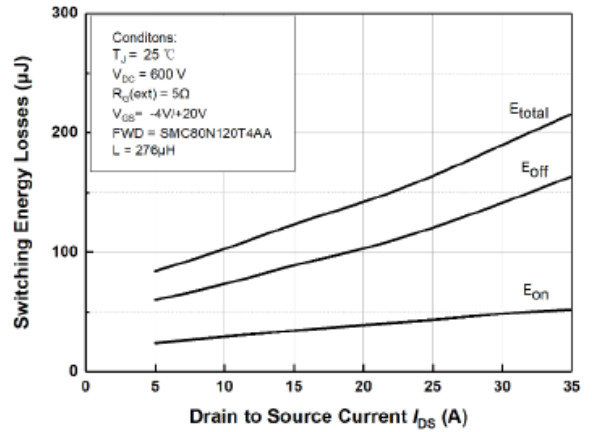


Figure 20. Clamped Inductive Switching Energy vs. Drain Current( $V_{DD} = 600V$ )

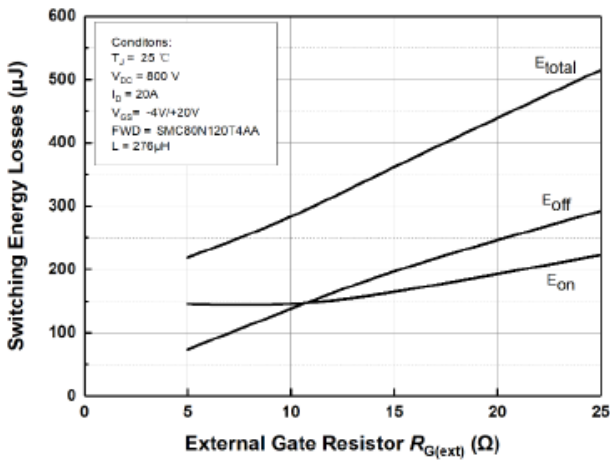


Figure 21. Clamped Inductive Switching Energy vs.  $R_{G(ext)}$

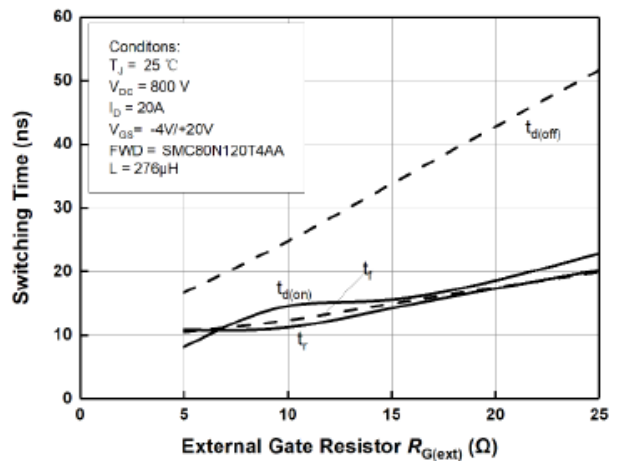


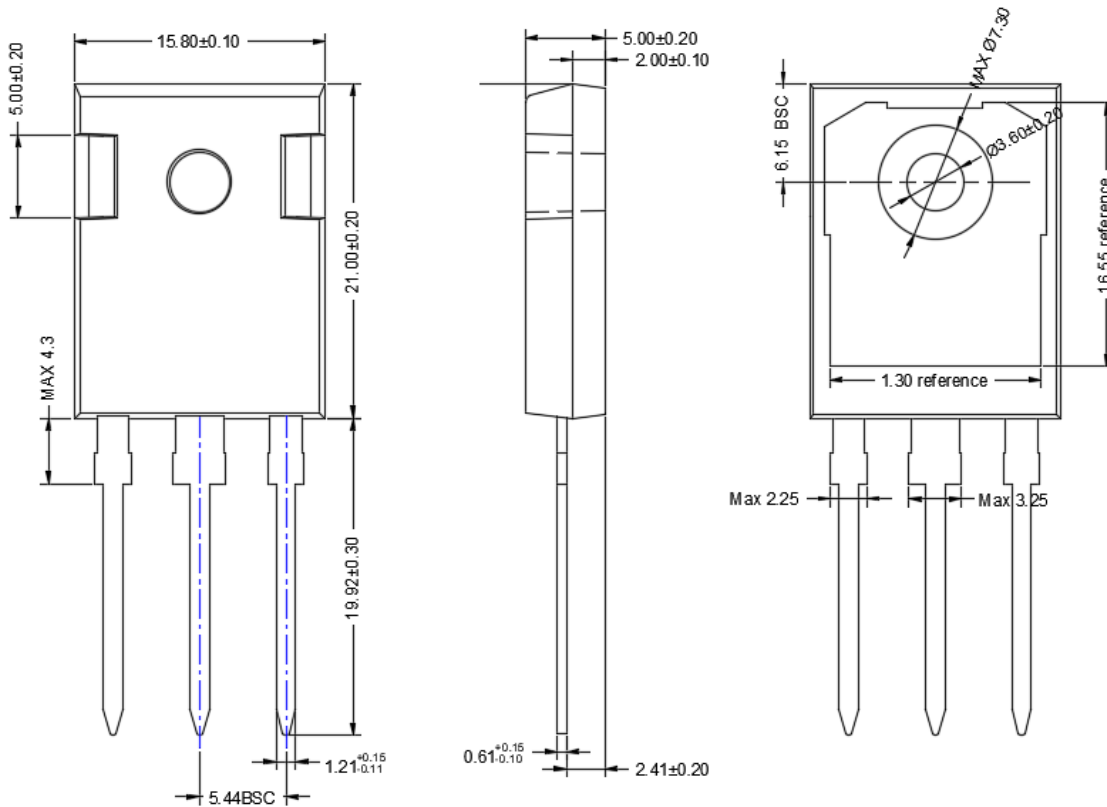
Figure 22. Switching Times vs.  $R_{G(ext)}$

6 Product Specifications and Packaging Models

DCC075M120G2C	TO-247-3	DCC075M120G2C
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## 7 Dimensions

### TO-247-3 PACK OUTLINE DIMENSIONS



## 8 Attentions

- Jiangsu Donghai Semiconductor Technology CO.,LTD. reserves the right to change the specification without prior notice! The customer should obtain the latest version of the information before making the order and verify that the information is complete and up to date.
- It is the responsibility of the purchaser for any failure or failure of any semiconductor product under certain conditions. It is the responsibility of the purchaser to comply with safety standards and to take safety measures in the system design and machine manufacturing of Donghai products in order to avoid potential risk of failure. Injury or property damage.
- Product promotion is endless, our company will be dedicated to provide customers with better products.

## 9 Appendix

Revision history:

Date	REV.	Description	Page
2023.03.19	1.0	Original	7